



Material Content Data Sheet



Sales Product Name		BAS 70 E6327		Issued		29. August 2013			
MA#		MA000504278							
Package		PG-SOT23-3-11		Weight*		8.79 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	noble metal	gold	7440-57-5	0.003	0.03		341		
	inorganic material	silicon	7440-21-3	0.026	0.29	0.32	2912	3253	
leadframe	non noble metal	chromium	7440-47-3	0.008	0.09		927		
	inorganic material	silicon	7440-21-3	0.001	0.01		62		
	non noble metal	titanium	7440-32-6	0.003	0.03		309		
wire	non noble metal	copper	7440-50-8	2.704	30.76	30.89	307573	308871	
	noble metal	gold	7440-57-5	0.007	0.08	0.08	760	760	
	encapsulation	organic material	carbon black	1333-86-4	0.058	0.66		6589	
		plastics	brominated resin	-	0.087	0.99		9884	
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.116	1.32		13179		
	plastics	epoxy resin	-	1.246	14.17		141672		
	inorganic material	silicondioxide	60676-86-0	4.287	48.75	65.89	487617	658941	
leadfinish	non noble metal	tin	7440-31-5	0.150	1.70	1.70	17020	17020	
plating	noble metal	silver	7440-22-4	0.098	1.12	1.12	11155	11155	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

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